

SYSTEM SPECIFICATIONS
Energy Range

VIISion 80 2 - 80 keV

VIISion 200 2 - 200 keV

Maximum Beam Current in End Station (mA, 0° to +7°)

<i>System</i>	Energy (keV)	B (mA)	BF₂ (mA)	P (mA)	As (mA)
<i>VIISion 80 and VIISion 200 (Drift)</i>	5	1.5	-	-	-
	10	6	4	6	6
	20	7	7	10	10
	30	7	8	14	14
	40	9	9	20	20
	50	10	9	25	25
	60	10	9	25	25
	70	10	9	25	25
	80	10	9	25	25
<i>VIISion 200 (Accel)</i>	100	10	9	25	18
	120	10	9	25	25
	200	10	9	25	25
<i>Multiple Charged ++</i>	≥80	0.7	-	4	-

Beam Current Stability ±10% after warmup; 10 µA minimum; ≤10 glitches/hour

 Dopant Species ¹¹B⁺, ⁴⁹BF₂⁺, ⁷⁵As⁺, ³¹P⁺
Implant Dose Accuracy

Specification Range 5E11 - 5E16

 Energy VIISion 80 10 - 80 keV
 VIISion 200 10 - 200 keV

Uniformity 1σ ≤0.5% (for 7° tilt angle)

Repeatability 1σ ≤0.7% (for 7° tilt angle)

Throughput

<u>200mm</u>	<u>150mm</u>	
200	220	(mechanical limit, 6 scans, 7° tilt, 1D beam profiler, wafers per hour)

Wafers per Disc

13 18

Wafer Breakage

≤1:40,000

Wafer Tilt

continuous range from + 7° to - 7°, automatic, recipe controlled

Wafer Twist

0° - 360°, ±2°, automatic, recipe controlled

Wafer Cooling

 VIISion 200: ≤100°C @ 3000 Watts
 VIISion 80: ≤ 80°C @ 2000 Watts

Particulate Control

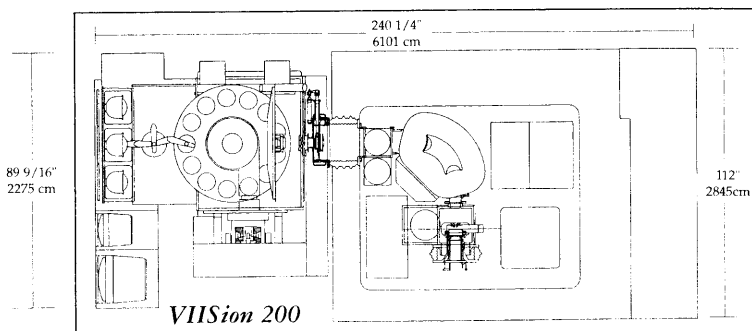
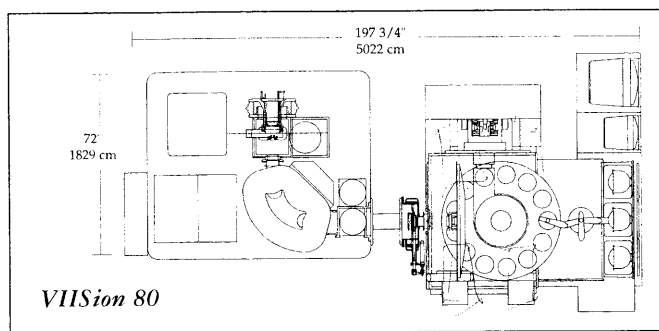
 ≤0.15 particles ≥0.2 µm added per cm² (mean value)

VIISion 80 and VIISion 200

High Current Ion Implantation System

BASIC SYSTEM CONFIGURATION	
<i>Wafer Handling</i>	• Horizontal loading wafer security system • Finger and fence wafer sites • Silicon-coated implant disc (specify 150 mm or 200mm) • Three 25-wafer capacity highly polished loadlocks • Dummy wafer loading with 7 wafers in each loadlock • Color monitor and camera for viewing wafer handling
<i>Ion Source and Gas Box</i>	• One dual-filament tungsten Bernas ion source (converted to vaporizer source if vaporizer kit option selected) • 80 kV extraction energy • 1500 psi gas box for three 4X process gas bottles, one 4X carrier gas bottle, and one 4X purge gas bottle
<i>Beamline</i>	• Variable, rotating mass slits • +7° to -7° automatic implant tilt angle • Magnetically suppressed Faraday • Plasma flood gun • One-dimensional ion beam profiler
<i>Control Electronics and System Software</i>	• 68030 computer with 240 MB hard drive, combination 3 1/2" floppy (1.44MB)/floptical (21 MB) drive • One 19" high resolution color touch screen interface • Color ink jet printer • Three-light signal tower • Auto setup and tuning, production scheduling, and system diagnostics
<i>Vacuum System</i>	• 4 CTI 250F end station cryopumps with 2 compressors remoted up to 40 feet • 1 Varian V250 loadlock turbopump • 1 Varian ICE beamline turbopump • 1 Hei source turbopump • • 1 Ebara dry mechanical pump source/terminal A07V (remoted on VIISion 80 only) • 1 Ebara dry mechanical pump end station (remoted) A255
<i>System Enclosure</i>	• Highly polished stainless steel cleanroom interface • Full peripheral radiation shielding, including lead flooring, lead shielding at critical enclosure areas • Hinged enclosure doors with safety interlocks (VIISion 200 only)
<i>Training and Documentation</i>	Enrollment of 1 student in the following training classes: • VIISion Operation 5 days • VIISion Maintenance 5 days • VIISion Electronics 13 days • Two sets of cleanroom-compatible operating manuals and drawing books
<i>Testing and Installation</i>	• 24-Hour uptime preshipment testing • Final acceptance testing • Installation

VIISion 80/VIISion 200 Facilities Requirements



	<i>Facilities Requirement</i>	<i>VIISion 80</i>	<i>VIISion 200</i>
Size & Weight	Total Installed Weight	23,972 lbs. 10,871 kG	37,287 lbs. 16,910 kG
	Outside Dimensions	197.8"L x 101.5"W x 104.6" H 5022mm x 2580mm x 2656mm	240 1/4"L x 112"W x 115"H 6101mm x 2845mm x 2920mm
Water	Inlet Pressure	40 - 100 PSIG 276 - 689 KPaG	40 - 100 PSIG 276 - 689 KPaG
	Flow	15 GPM 57 Liters/min	15 GPM 57 Liters/min
	Inlet Temperature, max	60° - 68°F 16° - 20°C	60° - 68°F 16° - 20°C
N₂ (Dry Nitrogen)	Pressure, min-max	50 - 100 PSIG 345 - 689 KPaG	50 - 100 PSIG 345 - 689 KPaG
	Flow	9 SCFM avg, 24 SCFM peak 250 l/min avg, 680 l/min peak	10 SCFM avg, 25 SCFM peak 283 l/min avg., 708 l/min peak
Compressed Air	Pressure, min-max	90 - 100 PSIG 621 - 689 KPaG	90 - 100 PSIG 621 - 689 KPaG
	Flow	4 SCFM avg, 12 SCFM peak 113 l/min avg, 340 peak	4 SCFM avg, 12 SCFM peak 113 l/min avg, 340 peak
Ventilation Air	Gas Box Exhaust	600 SCFM 17,000 l/min	600 SCFM 17,000 l/min
	Ion Source Exhaust	390 SCMF 11,000 l/min	390 SCMF 11,000 l/min
	Chamber Module Cryopump Exhaust	6 SCMF (peak per pump) 170 l/min	6 SCMF (peak per pump) 170 l/min
Heat Dissipation	To Water	58,000 BTU/Hr 17kW/hr (standby), 29 kW/hr (ready), 30 kW/hr (full power)	58,000 BTU/Hr 17kW/hr (standby), 29 kW/hr (ready), 30 kW/hr (full power)
	To Air	68,000 BTU/hr 20 kW/hr max	68,000 BTU/hr 20 kW/hr max
Operating Environment	Temperature, Air	60° - 73° F 15° - 23° C	60° - 73° F 15° - 23° C
Electrical	Electrical Requirements	208 VAC, 3-phase, 5-wire, 50/60 Hz; Full Load 45 kVA, Ready 35 kVA, Standby 15 kVA	208 VAC, 3-phase, 5-wire, 50/60 Hz; Full Load 55 kVA, Ready 45 kVA, Standby 25 kVA



Varian Ion Implant Systems
35 Dory Road • Gloucester, MA 01930 USA
TEL 508-281-2000 • FAX 508-283-5391

While these specifications are accurate at the time of printing, they are subject to change without notice

SEHS 0250/252 11/95